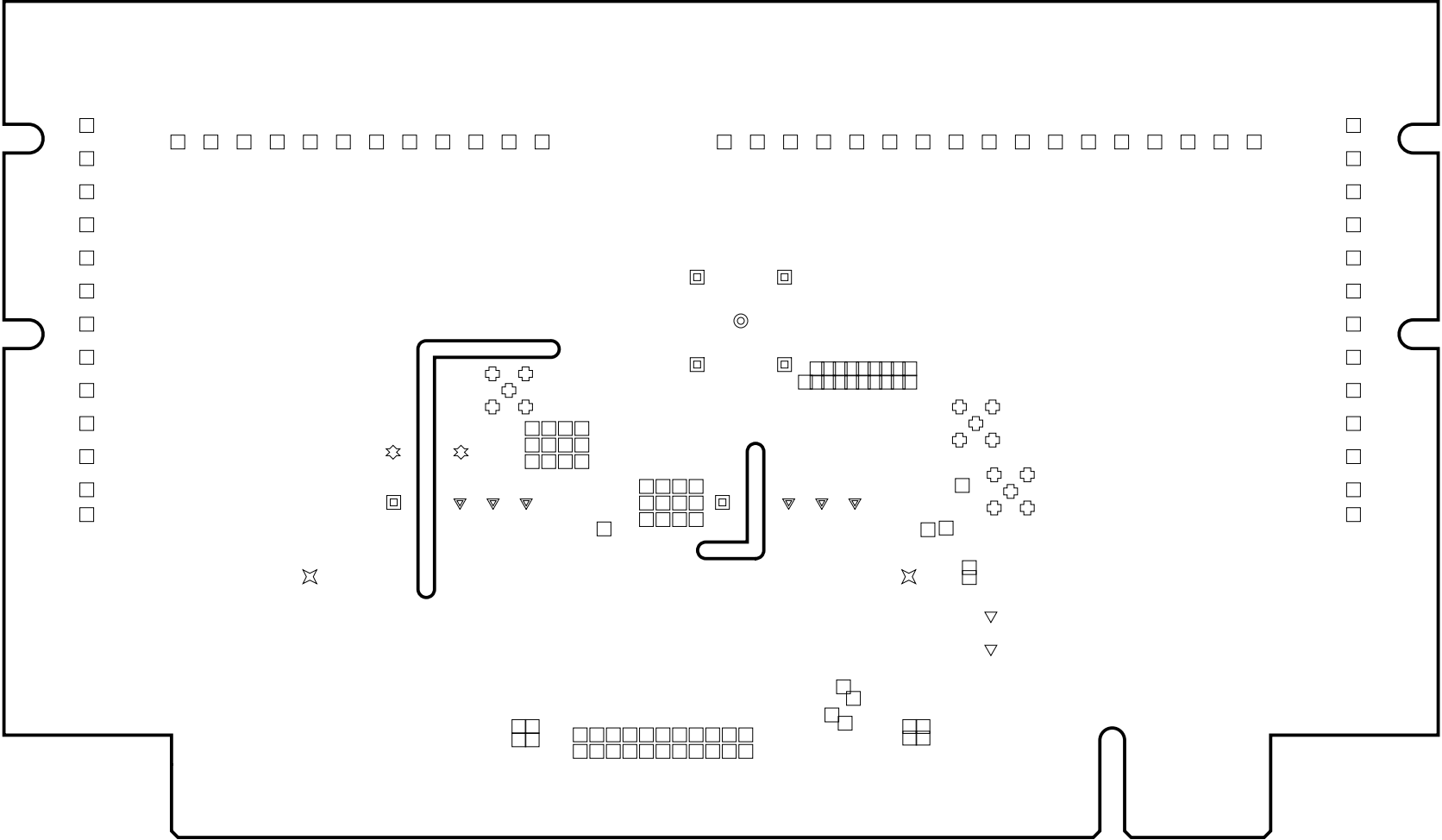



Drill Drawing View (Scale 2:1)



- Notes:
- 1. Fabricate per IPC 6012 Class II
  - 2. Material: FR4 equivalent.  
Tg>=170°
  - 3. Cu weight all layers: 4 oz.
  - 4. Total board thickness after plating: 0.062 +/- 8%
  - 5. Final finish: ENIG
  - 6. Soldermask both sides using photo-imagable process. Color: green
  - 7. Silkscreen both sides using non-conductive ink. Color : white
  - 8. All holes to be +/- 0.003 unless otherwise specified. Hole sizes are given after plating. Plated thru-hole shall have a min of 0.002 Cu internal plating.
  - 9. Remove all burrs and sharp edges 0.015 min.
  - 10. Surface finish: ENIG
-  No gold fingers required.

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
	Top Solder	0.4mil	Solder Resist	Solder Mask	GTS
CF-006	TOP	5.5mil		Signal	GTL
Core		10.0mil	Core-028	Dielectric	
CF-006	INNER1	5.5mil		Signal	G1
Core		21.0mil	Core-037	Dielectric	
CF-004	INNER2	5.5mil		Signal	G2
Core		10.0mil	Core-028	Dielectric	
CF-006	BOTTOM	5.5mil		Signal	GBL
Surface Material	Bottom Solder	0.4mil	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
	138	12.0mil	Plated	
	15	33.1mil	Plated	
	2	40.2mil	Plated	
	1	45.0mil	Plated	
	6	65.0mil	Plated	
	6	70.0mil	Plated	
	2	77.0mil	Plated	
	2	98.4mil	Plated	
	172 Total			



Title: K-pkg MOSFET Modular Accessory Board

Drawing No: MOD-PWR-MM-K-K\_ASY

Date: Sep. 2023 Size: B Revision: 3.1 Sheet: 1 of 3



Title: K-pkg MOSFET Modular Accessory Board

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Size: B

Revision: 3.1

Sheet: 2 of 3

